

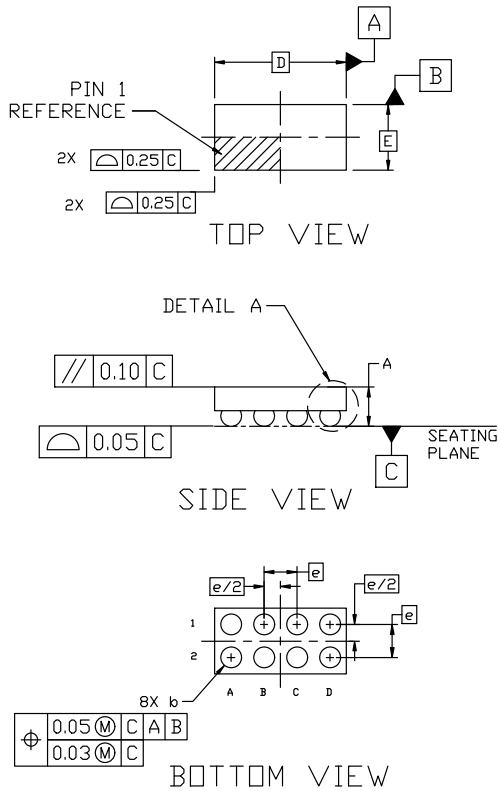
MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS



WLCSP8 2.0x1.0x0.601
CASE 567HD
ISSUE A

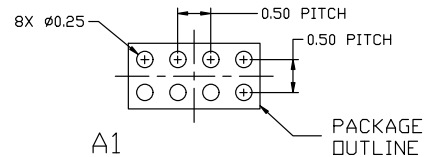
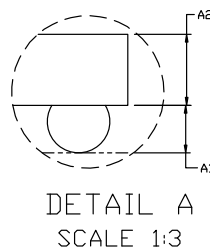
DATE 21 JUN 2022



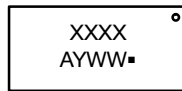
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.551	0.601	0.651
A1	0.216	0.241	0.266
A2	0.335	0.360	0.385
b	0.292	0.317	0.342
D	2.00 BSC		
E	1.00 BSC		
e	0.50 BSC		



GENERIC MARKING DIAGRAM*



- A = Assembly Location
- Y = Year
- WW = Work Week
- = Pb-Free Package

RECOMMENDED MOUNTING FOOTPRINT*

* For additional information on our Pb-Free strategy and soldering details, please download the DN Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	WLCSP8 2.0x1.0x0.601	PAGE 1 OF 1

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